MA3D750 (MA7D50), **MA3D750A** (MA7D50A)

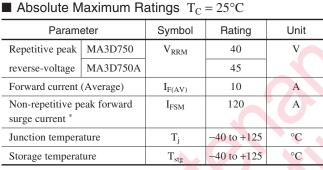
Silicon epitaxial planar type (cathode common)

For switching mode power supply

■ Features

- Low forward voltage V_F
- High dielectric breakdown voltage: > 5 kV
- Easy-to-mount, due to its V cut lead end

Param	eter	Symbol	Rating	Unit	
Repetitive peak	MA3D750	V _{RRM}	40	V	
reverse-voltage	MA3D750A		45		
Forward current (Average)		I _{F(AV)}	10	A	
Non-repetitive peak forward surge current *		I_{FSM}	120	A	
Junction temperature		T _j	-40 to +125	°C	
Storage temperat	ture	T _{stg}	-40 to +125	°C	



Unit: mm 2.9±0.2 1: Anode 2: Cathode (Common) 3: Anode TO-220D-A1 Package

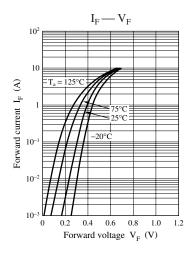
Note) *: Half sine wave; 10 ms/cycle

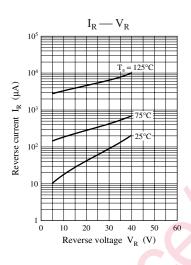
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

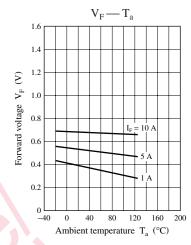
Paramete	er	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V_{F}	$I_F = 5 \text{ A}, T_C = 25^{\circ}\text{C}$			0.55	V
Reverse current	MA3D750	I_R	$V_R = 40 \text{ V}, T_C = 25^{\circ}\text{C}$			3	mA
	MA3D750A	SILC	$V_R = 45 \text{ V}, T_C = 25^{\circ}\text{C}$			3	
Thermal resistance (j	-c)	R _{th(j-c)}	.5			3.0	°C/W

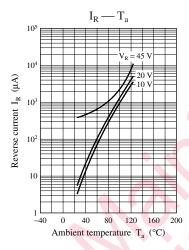
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 150 MHz.

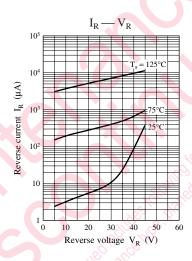
Note) The part numbers in the parenthesis show conventional part number.

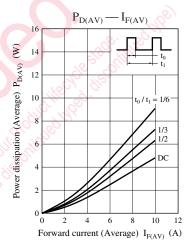


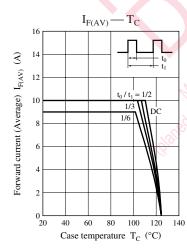












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